

L Number	Hits	Search Text	DB	Time stamp
9	3	electrodeposition adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 14:15
10	87107	frame with (elements or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 14:18
11	17912	(frame with (elements or chip)) and (encapsulant or resin or sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 14:20
12	8464	((frame with (elements or chip)) and (encapsulant or resin or sealing)) and (cut or remove or removal or cutting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 14:23
13	1265	((frame with (elements or chip)) and (encapsulant or resin or sealing)) and ((cut or remove or removal or cutting) with (metal or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 14:48
14	1	("6278177").PN.	USPAT	2002/05/14 15:43
15	148	438/464.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:52
16	520	438/106.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:53
17	62	438/617.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:56
18	173	438/112.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:57
19	324	438/124.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:58
20	435	438/127.ccls. and (resin or sealing, or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:58
21	299	438/107.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 15:58
22	96	438/110.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/14 16:04

23	203	438/113.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:05
24	153	438/121.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:05
25	422	438/123.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:05
26	324	438/124.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:06
27	52	438/461.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:11
28	74	438/459.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:13
29	148	438/464.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:13
30	423	257/784.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:14
31	2280	257/787.ccls. and (resin or sealing or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/14 16:14